CLAIMS

I claim:

1. A method of making a memory card card, comprising the steps of:

adding circuit elements to a circuit board, said circuit board includes a set of test terminals;

testing one or more of said circuit elements using said test terminals; and

covering said test terminals with a conformal contact coating in order to prevent access to said test terminals.

2. A method according to claim 1, wherein:

said step of covering includes applying a liquid directly to a first surface of said circuit board.

3. A method according to claim 2, wherein:

said liquid includes a solder mask.

4. A method according to claim 2, wherein:

said liquid includes a photoresist.

5. A method according to claim 2, wherein:

said liquid includes a thermoplastic.

6. A method according to claim 2, wherein:

said liquid includes an epoxy.

7. A method according to claim 2, wherein:
said liquid includes polyimide.

8. A method according to claim 2, wherein:
said liquid is applied using a screen printing process.

9. A method according to claim 1, wherein:
said step of covering includes applying a film directly to a first surface of said circuit board.

10. A method according to claim 9, wherein:
said film includes an adhesive on one surface.

11. A method according to claim 9, wherein:
said film includes mylar.

12. A method according to claim 9, wherein:
said film includes polyimide.

13. A method according to claim 1, wherein:
said step of adding circuit elements includes adding a flash memory array to said circuit board.

14. A method according to claim 1, wherein:
said step of adding circuit elements includes mounting a first die on said circuit board and mounting a second die on said first die.

15. A method according to claim 14, wherein:

said first die includes a flash memory array and said second die includes a controller.

16. A method according to claim 14, wherein:

said first die is wire bonded to said circuit board; and

said second die is wire bonded to said circuit board.

17. A method according to claim 1, wherein:

said circuit board includes a conductive layer and a first portion of said conductive layer forms said test terminals.

18. A method according to claim 17, wherein:

a second portion of said conductive layer forms user terminals;

said user terminals are positioned on an outside surface of said memory card; and

said user terminals are in communication with at least a subset of said circuit elements.

19. A method according to claim 1, wherein:

said step of adding circuit elements includes performing a transfer mold process to encapsulate said circuit elements without covering said test terminals.

20. A method according to claim 1, wherein:

said step of covering is performed after said circuit board is removed from a strip of circuit boards.

21. A method according to claim 1, wherein:

said step of covering is performed before said circuit board is removed from a strip of circuit boards.

22. A method according to claim 1, wherein:

said memory card is a flash memory card.

23. A method according to claim 22, wherein:

said step of covering includes applying a liquid directly to a first surface of said circuit board.

24. A method according to claim 22, wherein:

said step of covering includes applying a film directly to a first surface of said circuit board.

25. A method of making a peripheral card, comprising the steps of:

adding circuit elements to a plurality of circuit boards of a strip of circuit boards, each of said plurality of circuit boards includes a set of test terminals;

separating said connected circuit boards;

testing said circuit elements of said circuit boards using said test terminals; and

applying a conformal contact coating on a first surface of each of said circuit boards to cover said test terminals and prevent access to said test terminals such that a particular circuit board has its test terminals covered after said particular circuit board has been tested.

26. A method according to claim 25, wherein:

said step of separating is performed after said step of applying.

27. A method according to claim 25, wherein:

said step of separating is performed prior to said step of applying.

28. A method according to claim 25, wherein:

said step of applying includes applying a liquid directly to a first surface of said circuit boards.

29. A method according to claim 25, wherein:

said step of applying includes applying a film directly to a first surface of said circuit boards.

30. A method according to claim 25, wherein:

said step of adding circuit elements includes mounting a first die on a first circuit board and mounting a second die on said first die;

said first die includes a flash memory array and said second die includes a controller;

said first die is wire bonded to said first circuit board; and

said second die is wire bonded to said first circuit board.

31. A method according to claim 25, wherein:

said peripheral card is a memory card.

32. A peripheral card manufactured according to a process comprising the steps of:

adding circuit elements to a circuit board, said circuit board includes a set of test terminals;

testing one or more of said circuit elements using said test terminals; and

applying a conformal contact coating on a first surface of said circuit board to cover said test terminals and prevent access to said test terminals.

33. A peripheral card according to claim 32, wherein:

said step of applying includes applying a liquid directly to a first surface of said circuit board.

34. A peripheral card according to claim 32, wherein:

said step of applying includes applying a film directly to a first surface of said circuit board.

35. A peripheral card according to claim 32, wherein:

said circuit board includes a first die mounted on said circuit board and a second die mounted on said first die;

said first die includes a flash memory array and said second die includes a controller;

said first die is wire bonded to said circuit board; and

said second die is wire bonded to said circuit board.

36. A peripheral card according to claim 32, wherein:

said circuit board includes a conductive layer;

a first portion of said conductive layer forms said test terminals;

a second portion of said conductive layer forms user terminals;

said user terminals are positioned on an outside surface of said peripheral card; and

said circuit elements are encapsulated by a transfer mold process without covering

said test terminals.

37. A peripheral card according to claim 32, wherein:

said peripheral card is a memory card.

38. A peripheral card, comprising:

a circuit board;

circuit elements on said circuit board;

a set of user terminals on said circuit board, said user terminals are in communication with at least a subset of said circuit elements;

a set of test terminals on said circuit board, said test terminals are in communication with one or more of said circuit elements;

an enclosure that covers a portion of said circuit board and said circuit elements without covering said set of user terminals and said set of test terminals; and

a conformal contact coating on a first surface of said circuit board covering said test terminals and preventing access to said test terminals.

39. A peripheral card according to claim 38, wherein:

said conformal contact coating is applied as a liquid directly to said first surface of said circuit board.

40. A peripheral card according to claim 38, wherein:

said conformal contact coating includes a film that is applied directly to said first surface of said circuit board.

41. A peripheral card according to claim 38, wherein:

said circuit elements board include a first die mounted on said circuit board and a

second die mounted on said first die.

42. A peripheral card according to claim 41, wherein:
said first die is wire bonded to said circuit board; and
said second die is wire bonded to said circuit board.

43. A peripheral card according to claim 42, wherein:
said first die includes a flash memory array and said second die includes a controller.

44. A peripheral card according to claim 41, wherein:
said first die includes a flash memory array and said second die includes a controller.

45. A peripheral card according to claim 38, wherein:
said circuit board includes a conductive layer;
a first portion of said conductive layer forms said test terminals;
a second portion of said conductive layer forms said user terminals; and
said user terminals are positioned on an outside surface of said peripheral card.

46. A peripheral card according to claim 38, wherein:
said peripheral card is a memory card.

47. A method performed for a peripheral card, comprising the steps of:
testing one or more circuit elements of a first peripheral card using one or more test terminals of said first peripheral card; and
covering said test terminals with a conformal contact coating in order to prevent

access to said test terminals.

48. A method according to claim 47, wherein:

said step of covering includes applying a liquid directly to said first peripheral card.

49. A method according to claim 47, wherein:

said step of covering includes applying a film directly to said first peripheral card.

50. A method according to claim 47, wherein:

said circuit elements include a flash memory array.

51. A method according to claim 47, wherein:

said first peripheral card is a memory card.